

## **ABSTRACT**

The disclosure discloses a special low-flowability encapsulant film for heterojunction cell modules and a preparation method thereof. Raw materials for preparing the encapsulant film include, in parts by weight: 40-80 parts of matrix resin, 20-60 parts of functional resin, 0.01-0.6 parts of main crosslinker, 0.2-0.8 parts of assistant crosslinker, 0.01-1 part of anti-aging agent, and 0-1 part of silane coupling agent. The functional resin is a POE graft material. The encapsulant film prepared in the disclosure has low flowability, and also has a low enough modulus to effectively reduce micro-cracks of cells produced during lamination. Moreover, the encapsulant film has good and long-lasting adhesion to heterojunction cells, and is suitable for encapsulation of heterojunction modules.

No Figure